



Product Change Notification - ASER-15HSFK728

Date:

22 Nov 2019

Product Category:

Broadband Gateway

Affected CPNs:**Notification subject:**

CCB 3886, 3886.001, and 3886.002 Initial Notice: Qualification of MMT as an additional assembly site for selected Microsemi products available in 64L VQFN (9x9x1.0mm), 56L VQFN (8x8x1.0mm), & 40L VQFN (6x6x1.0mm) packages.

Notification text:**PCN Status:**

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected Microsemi products available in 64L VQFN (9x9x1.0mm), 56L VQFN (8x8x1.0mm), & 40L VQFN (6x6x1.0mm) packages.

Pre Change:

Assembled at ASEM using PdCu bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material or assembled at UNIC using CuPdAu bond wire, 8290 die attach, and G770HP mold compound material. Use of bakeable tray packing material in MSL 3 requirements.

Post Change:

Assembled at ASEM using PdCu bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material, assembled at UNIC using CuPdAu bond wire, 8290 die attach, and G770HP mold compound material, or assembled at MMT using CuPdAu wire material, 3280 die attach, and G700LTD mold compound material. Use of non-bakeable tray packing material in MSL 1 requirements.

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	ASE Group - Malaysia (ASEM)	Unisem Chengdu Co.,Ltd. (UNIC)	ASE Group - Malaysia (ASEM)	Unisem Chengdu Co.,Ltd. (UNIC)	Microchip Technology Thailand (Branch)



					(MMT)
Wire material	PdCu	CuPdAu	PdCu	CuPdAu	CuPdAu
Die attach material	CRM1076DS	8290	CRM1076DS	8290	3280
Molding compound material	CEL-9240HF10AK-G1	G770HP	CEL-9240HF10AK-G1	G770HP	G700LTD
Lead frame material	C194	C194	C194	C194	C194
MSL Level	MSL 3	MSL 3	MSL 3	MSL 3	MSL 1
Assembly Shipping Media	See Pre and Post Change attachment.				
Tray Color	See Pre and Post Change attachment.				
Tray Dimension (LxWxH)	See Pre and Post Change attachment.				
Tray Photos	See Pre and Post Change attachment.				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity and on-time delivery by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

December 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

[illegible]

**Method to Identify Change:**

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

October 24, 2019: Issued initial notification.

November 22, 2019: Reissued initial notification. Corrected Pre and Post Change Attachment to accurately reflect the comparison between the different assembly sites.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_ASER-15HSFK728 - Pre and Post Change Summary.pdf](#)

[PCN_ASER-15HSFK728_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

LE88262TQC
LE88262TQCT
LE88266TQC
LE88266TQCT
LE88286TQC
LE88286TQCT
ZL88103LDF1
ZL88103LDG1
ZL88601LDF1
ZL88601LDG1
ZL88602LDF1
ZL88602LDG1
ZL88701LDF1
ZL88701LDG1
ZL88702LDF1
ZL88702LDG1
ZL88801LDF1
ZL88801LDG1
LE9661WQC
LE9661WQCT
LE9662WQC
LE9662WQCT
LE9672WQC
LE9672WQCT
ZL88105LDF1
ZL88105LDG1
LE9540CUQC
LE9540CUQCT
LE9540DUQC
LE9540DUQCT
LE9541CUQC
LE9541CUQCT
LE9541DUQC
LE9541DUQCT